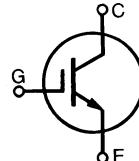


HiPerFAST™ IGBT

IXGH24N50B
IXGH24N60B

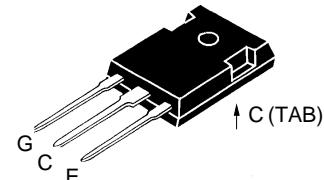
V_{CES}	$I_{C(25)}$	$V_{CE(sat)}$	t_{fi}
500 V	48 A	2.3 V	80 ns
600 V	48 A	2.5 V	80 ns

Preliminary data



Symbol	Test Conditions	Maximum Ratings		
		24N50	24N60	
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	500	600	V
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	500	600	V
V_{GES}	Continuous		± 20	V
V_{GEM}	Transient		± 30	V
I_{C25}	$T_c = 25^\circ\text{C}$	48	A	
I_{C90}	$T_c = 90^\circ\text{C}$	24	A	
I_{CM}	$T_c = 25^\circ\text{C}$, 1 ms	96	A	
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 22 \Omega$ Clamped inductive load, $L = 100 \mu\text{H}$	$I_{CM} = 48$ @ $0.8 V_{CES}$	A	
P_c	$T_c = 25^\circ\text{C}$	150	W	
T_J		-55 ... +150	$^\circ\text{C}$	
T_{JM}		150	$^\circ\text{C}$	
T_{stg}		-55 ... +150	$^\circ\text{C}$	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$	
M_d	Mounting torque (M3)	1.13/10	Nm/lb.in.	
Weight		6	g	

TO-247 AD



G = Gate, C = Collector,
E = Emitter, TAB = Collector

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
BV_{CES}	$I_c = 250 \mu\text{A}$, $V_{GE} = 0 \text{ V}$	24N50 24N60	500 600	V V
$V_{GE(th)}$	$I_c = 250 \mu\text{A}$, $V_{CE} = V_{GE}$		2.5	5 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		200 μA 1 mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			± 100 nA
$V_{CE(sat)}$	$I_c = I_{C90}$, $V_{GE} = 15 \text{ V}$	24N50 24N60		2.3 V 2.5 V

Features

- International standard packages JEDEC TO-247 AD
- High frequency IGBT
- High current handling capability
- 3rd generation HDMOS™ process
- MOS Gate turn-on
 - drive simplicity

Applications

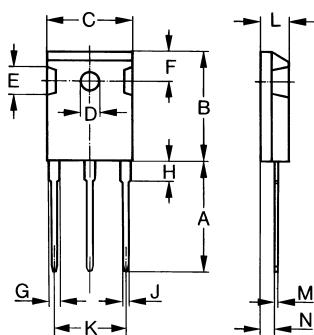
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies

Advantages

- High power density
- Switching speed for high frequency applications
- Easy to mount with 1 screw (insulated mounting screw hole)

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
g_{fs}	$I_C = I_{C90}$; $V_{CE} = 10 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$	9	13	S
C_{ies} C_{oes} C_{res}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$	1500		pF
		135		pF
		40		pF
Q_g Q_{ge} Q_{gc}	$I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $V_{CE} = 0.5 V_{CES}$	90	120	nC
		11	15	nC
		30	40	nC
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 100 \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 10 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	25		ns
		15		ns
		0.6		mJ
		150	200	ns
		80	150	ns
		0.62		mJ
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 100 \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 10 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	25		ns
		15		ns
		0.8		mJ
		250		ns
		100		ns
		0.9		mJ
R_{thJC}		0.83		K/W
		0.25		K/W

TO-247 AD (IXGH) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

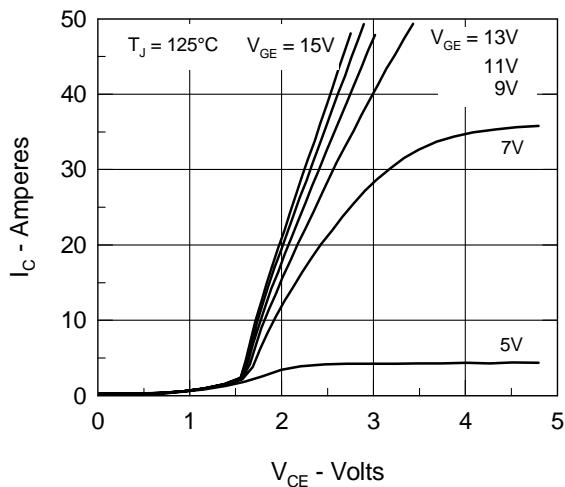


Fig. 1. Saturation Voltage Characteristics

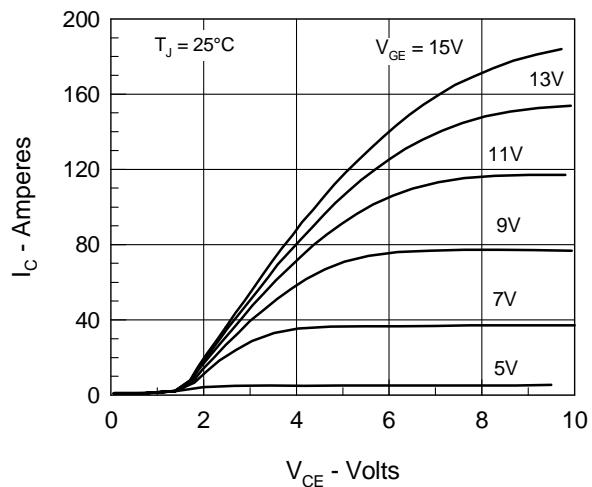


Fig. 2. Extended Output Characteristics

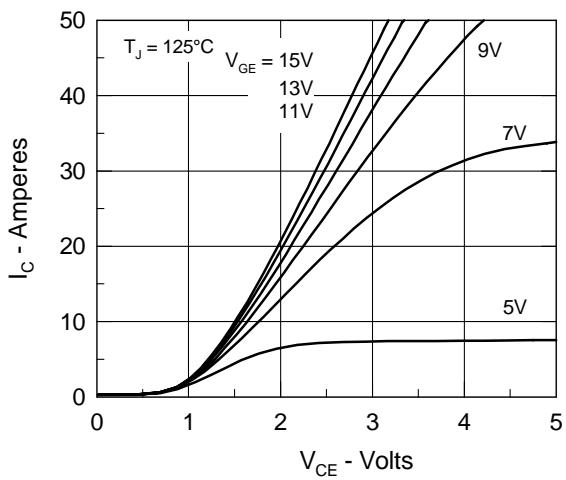


Fig. 3. Saturation Voltage Characteristics

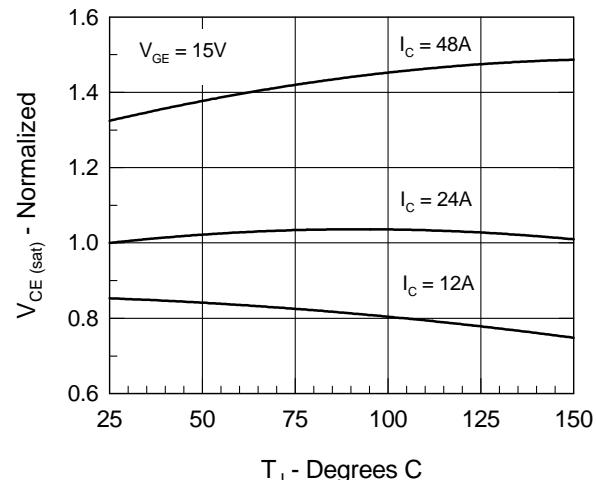
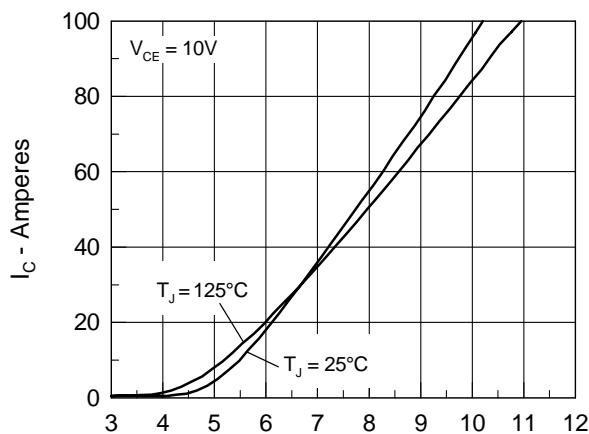
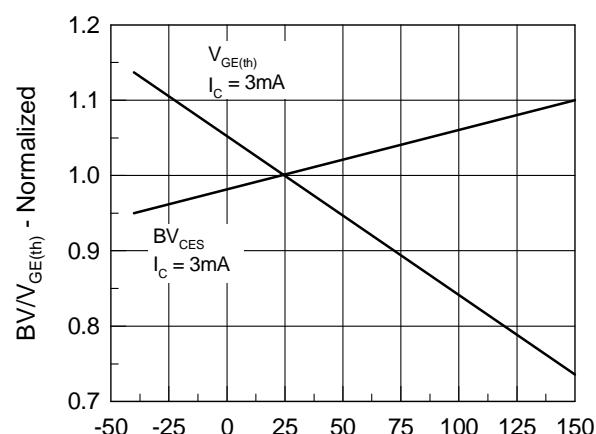
Fig. 4. Temperature Dependence of $V_{CE(sat)}$ 

Fig. 5. Admittance Curves

Fig. 6. Temperature Dependence of BV_{DSS} & $V_{GE(th)}$

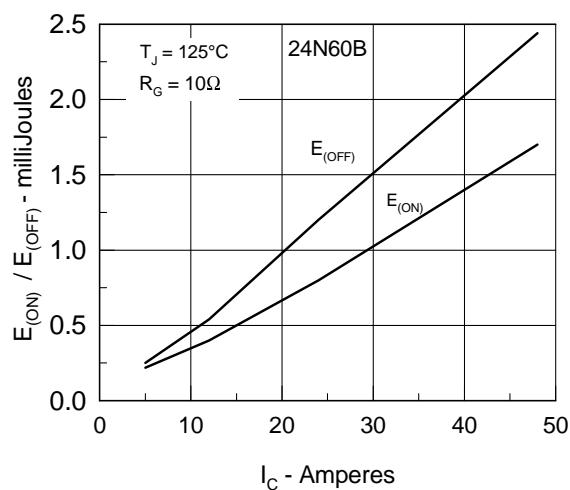
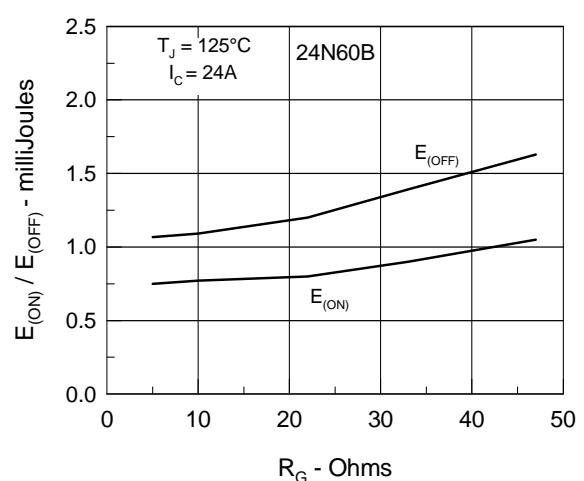
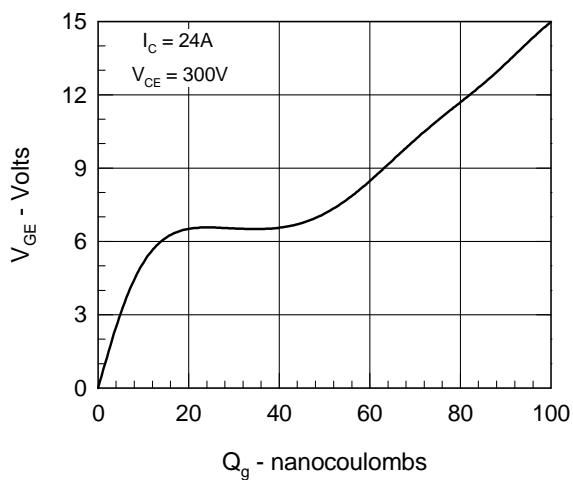
Fig. 7. Dependence of t_{fi} and $E_{(OFF)}$ on I_c .Fig. 8. Dependence of t_{fi} and $E_{(OFF)}$ on R_G .

Fig. 9. Gate Charge

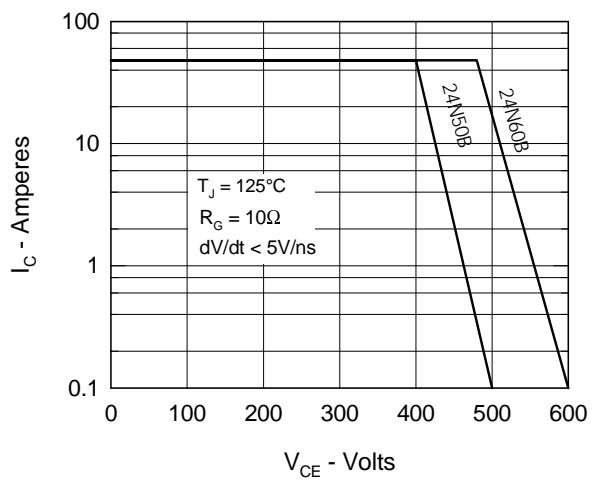


Fig. 10. Turn-off Safe Operating Area

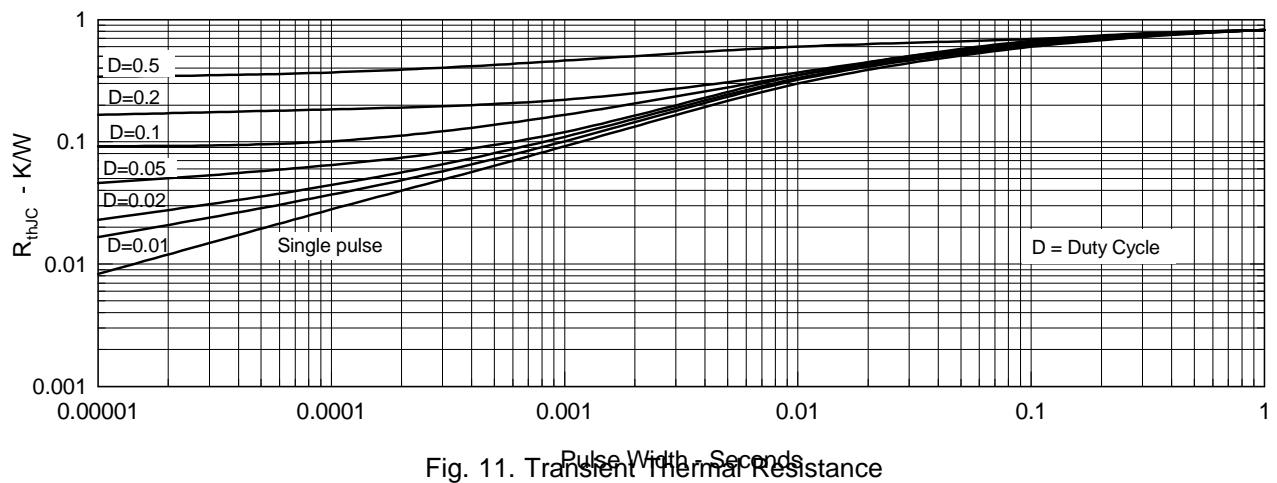


Fig. 11. Transient Thermal Resistance